

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property  
Organization  
International Bureau

(43) International Publication Date  
22 December 2022 (22.12.2022)



(10) International Publication Number  
**WO 2022/265822 A1**

- (51) International Patent Classification:  
C23C 14/50 (2006.01) C23C 14/56 (2006.01)
- (21) International Application Number:  
PCT/US2022/030502
- (22) International Filing Date:  
23 May 2022 (23.05.2022)
- (25) Filing Language: English
- (26) Publication Language: English
- (30) Priority Data:  
17/351,535 18 June 2021 (18.06.2021) US
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(81) Designated States (unless otherwise indicated, for every  
kind of national protection available): AE, AG, AL, AM,  
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,  
CA, CH, CL, CN, CO, CR, CU, CZ, DE, DJ, DK, DM, DO,  
DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN,  
HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE, KG, KH,  
KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU, LY, MA,  
MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI,  
NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU,  
RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ, TM,

(54) Title: PROCESS KIT HAVING TALL DEPOSITION RING AND SMALLER DIAMETER ELECTROSTATIC CHUCK (ESC)  
FOR PVD CHAMBER

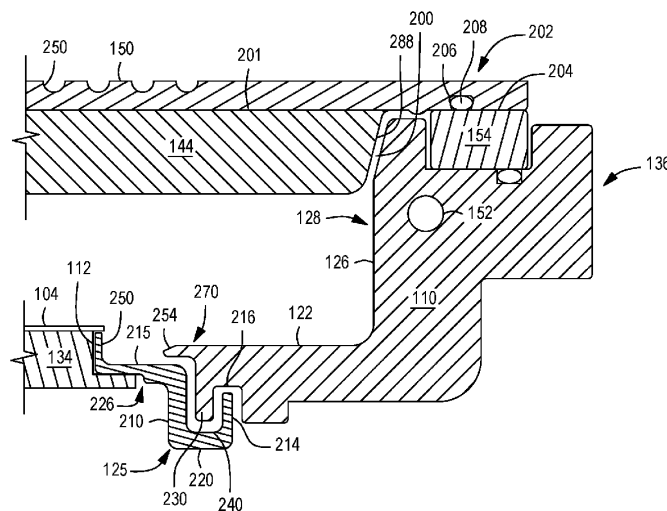


FIG. 2

(57) Abstract: Embodiments of process kits are provided herein. In some embodiments, a process kit, includes: a deposition ring configured to be disposed on a substrate support, the deposition ring comprising: an annular band having an upper surface and a lower surface, the lower surface including a step between a radially inner portion and a radially outer portion, the step extending downward from the radially inner portion to the radially outer portion; an inner lip extending upwards from the upper surface of the annular band and adjacent an inner surface of the annular band, and wherein an outer surface of the inner lip extends radially outward and downward from an upper surface of the inner lip to the upper surface of the annular band; a channel disposed radially outward of the annular band; and an outer lip extending upwardly and disposed radially outward of the channel.

[Continued on next page]

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TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA, ZM, ZW.

**(84) Designated States** (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, ST, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, KM, ML, MR, NE, SN, TD, TG).

**Published:**

— with international search report (Art. 21(3))